

3. The transducer of claim 1, wherein the transducer I/O lead is configured to contact the integrated circuit I/O lead at a transducer surface substantially parallel to a mounting surface of the substrate.

4. The transducer of claim 1, wherein the transducer I/O lead is configured to contact a pin I/O lead of the integrated circuit.

5. The transducer of claim 1, wherein the transducer I/O lead is configured to contact a solder ball lead of the integrated circuit.

6. The transducer of claim 1, wherein the transducer I/O lead is configured to contact the integrated circuit I/O lead at a transducer surface adjacent to a mounting surface of the substrate.

7. The transducer of claim 1, further comprising a power input lead connectable to a power line of the substrate.

8. The transducer of claim 1, further comprising a transductional device.

9. The transducer of claim 1, wherein the transductional device is an opto-electronic device.

10. The transducer of claim 1, wherein the transductional device is an electronic device.